

05-29-2003

Docket No. N1085-00148

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(Rev. 03/01)

OMB No. 0651-0027 (exp. 5/31/2002)

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U.S. DEPARTMENT OF COMMERCE
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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Zhen-Cheng Wu
Yung-Cheng Lu
Syun-Ming Jang

5-19-03

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: May 19, 2003

2. Name and address of receiving party(ies)

Name: Taiwan Semiconductor Manufacturing Co., Ltd.

Internal Address: _____

Street Address: 121 Park Avenue 3

Science-Based Industrial Park, Hsin-Chu Taiwan, R.O.C.

City: _____ State: _____ Zip: _____

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

10441511

If this document is being filed together with a new application, the execution date of the application is: 05/19/03

A. Patent Application No.(s) _____

B. Patent No.(s) _____

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Richard A. Paikoff

Internal Address: _____

Street Address: Duane Morris LLP

1650 Market Street

City: Philadelphia State: PA Zip: 19103-7396

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

04-1679

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9. Signature.

Richard A. Paikoff

Name of Person Signing

Richard A. Paikoff

Signature

May 19, 2003

Date

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:
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PATENT
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ASSIGNMENT AND AGREEMENT

For value received, we, **Zhen-Cheng Wu, Yung-Cheng Lu, and Syun-Ming Jang**, hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at 121 Park Avenue 3, Science-Based Industrial Park, Hsin-Chu Taiwan, R.O.C., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **STRUCTURE FOR IMPROVING INTERLEVEL CONDUCTOR CONNECTIONS** described in an application for Letters Patent of the United States executed on even date herewith, and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Dated: 5/19/03Zhen-Cheng Wu
Zhen-Cheng Wu

Residence: 3Fl., No. 136, Lane 160, Gaotzuei Rd. Hsinchu, 300 Taiwan.

Dated: 5/19/03Yung-Cheng Lu
Yung-Cheng Lu

Residence: 2F, No. 4, Ln. 114, Sec. 7, Chungshan N. Rd., Taipei, Taiwan

Dated: 5/19/03Syun-Ming Jang
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Residence: 7F, 83 N. Kuan-Hua St., Hsin-Chu, Taiwan. ROC

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TOTAL P.04

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